

MTB0990A 9.7-10.1 GHz Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple

Applications

Wireless Infrastructure applications

Part Dimensions: 9.0 x 2.5 x× 3.1 mm • 0.15 g Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared other bandpass filter technologies.

Electrical Specifications

| • | | | | |
|--|--------------------|--------------------|------------------|------------------------------|
| Parameter | Frequency (GHz) | Typical at 25°C | Spec. at 25°C | Spec. over -40°C to +85°C |
| Nominal Impedance | - | 50 ohms | - | - |
| Average Input Power | - | - | - | 2.0 Watt max |
| Peak Input Power | - | - | - | 20 Watt max |
| Input-Output Response | | | | |
| Passband Insertion Loss (single point) | 9.70 - 10.10 | 2.5 dB | 3.0 dB min | 3.0 dB min |
| Passband Return Loss | 9.70 - 10.10 | 14 dB | 12 dB min | 12 dB min |
| Group Delay Variation (Max-Min) | 9.70 - 10.10 | 3.0 ns | 10 ns max | 10 ns max |
| Attenuation: | 1-9.22 | 34 dB | 30 dB min | 30 dB min |
| | 9.50 | 33 dB | 20 dB min | 20 dB min |
| | 9.60 | 11 dB | 10 dB min | 10 dB min |
| | | | | |
| | 10.20 | 10.5 dB | 10 dB min | 10 dB min |
| | 10.30 | 28 dB | 20 dB min | 20 dB min |
| | 10.58 | 34 dB | 30 dB min | 30 dB min |
| | | | | |

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances. Specification AllowanceInsertion Loss0.1 dBReturn Loss1.0 dBAttenuation1.0 dB

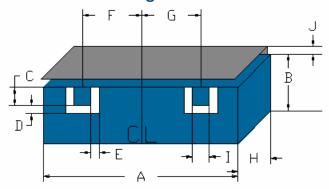
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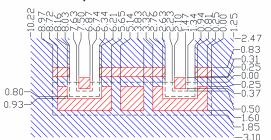
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Mechanical Drawing



PCB Layout







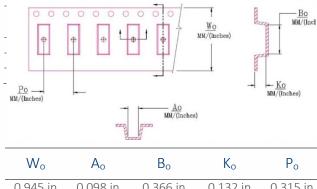
Nominal Tolerance Dim. (±mm or Max) (mm) Α 8.97 max В 1.67 max C 0.50 0.13 D 0.30 0.13 Е 0.40 0.13 F 2.70 0.13 G 2.70 0.13 Н 3.10 max 0.89 0.13 0.63 0.20

IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads and the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow incl. 120s of soak at 217°C, and up to 30 sec peak at 241°C.

Packaging and Marking



| W_{o} | A_{o} | Bo | Ko | Po |
|----------|----------|----------|----------|----------|
| 0.945 in | 0.098 in | 0.366 in | 0.132 in | 0.315 in |
| 24.0 mm | 2.50 mm | 9.30 mm | 3.35 mm | 8.0 mm |
| • | | | | |

Electrical Response

